

preliminary

Schottky Diode Gen 2

V_{RRM}	=	100V
I_{FAV}	=	300A
V_F	=	0.88V

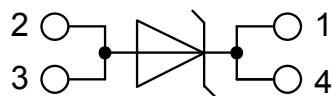
High Performance Schottky Diode
 Low Loss and Soft Recovery
 Single Diode

Part number

DSA300I100NA



Backside: Isolated

**Features / Advantages:**

- Very low V_F
- Extremely low switching losses
- Low I_{rm} values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

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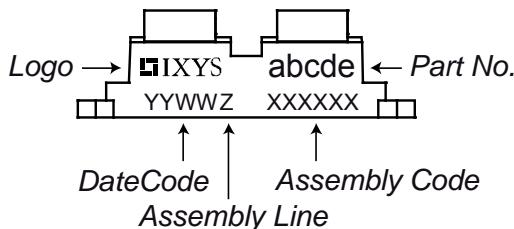
Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			100	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			100	V
I_R	reverse current, drain current	$V_R = 100 V$ $V_R = 100 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		3 30	mA
V_F	forward voltage drop	$I_F = 300 A$ $I_F = 600 A$ $I_F = 300 A$ $I_F = 600 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.99 1.30 0.88 1.21	V
I_{FAV}	average forward current	$T_C = 95^\circ C$ rectangular	$T_{VJ} = 150^\circ C$		300	A
I_F	threshold voltage slope resistance	} for power loss calculation only		$T_{VJ} = 150^\circ C$	0.53 1.09	V mΩ
R_{thJC}	thermal resistance junction to case				0.15	K/W
R_{thCH}	thermal resistance case to heatsink			0.10		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		830	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}; V_R = 0 V$	$T_{VJ} = 45^\circ C$		4.80	kA
C_J	junction capacitance	$V_R = 12 V$ f = 1 MHz	$T_{VJ} = 25^\circ C$		4.86	nF

Package SOT-227B (minibloc)

Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal ¹⁾			150	A
T_{stg}	storage temperature		-40		150	°C
T_{VJ}	virtual junction temperature		-40		150	°C
Weight				30		g
M_D	mounting torque		1.1		1.5	Nm
M_T	terminal torque		1.1		1.5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	10.5	3.2		mm
$d_{Spb/Abp}$		terminal to backside	8.6	6.8		mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000 2500			V V

¹⁾ I_{RMS} is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.

Product Marking



Part number

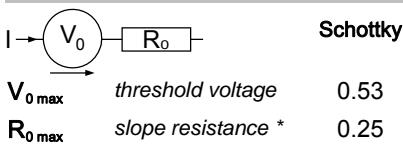
D = Diode
S = Schottky Diode
A = low VF
300 = Current Rating [A]
I = Single Diode
100 = Reverse Voltage [V]
NA = SOT-227B (minibloc)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSA300I100NA	DSA300I100NA	Tube	10	509813

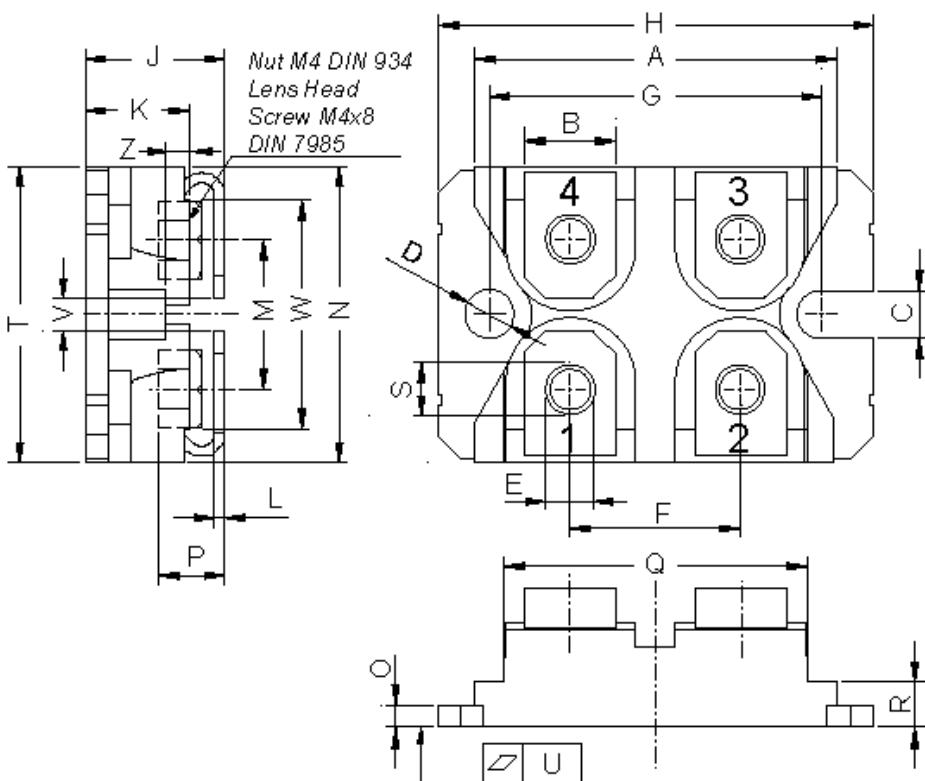
Similar Part	Package	Voltage class
DSA300I45NA	SOT-227B (minibloc)	45
DSA300I200NA	SOT-227B (minibloc)	200

Equivalent Circuits for Simulation

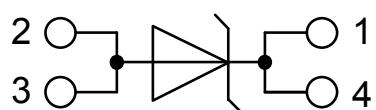
* on die level

 $T_{VJ} = 150^\circ\text{C}$ 

Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



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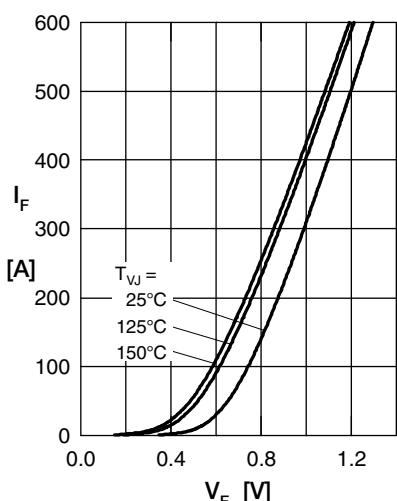


Fig. 1 Max. forward voltage drop characteristics

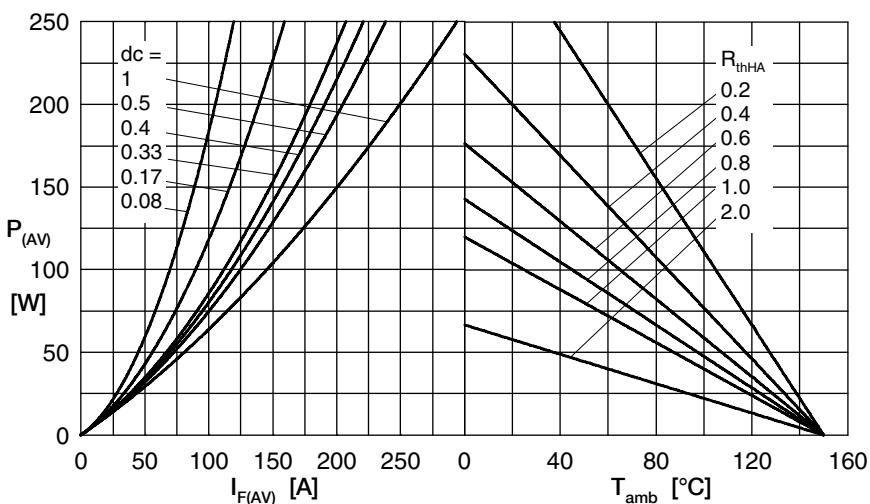
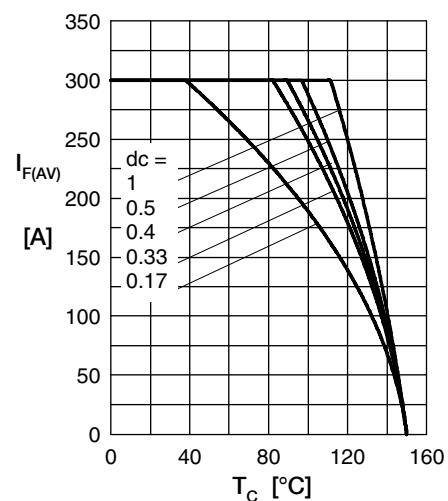
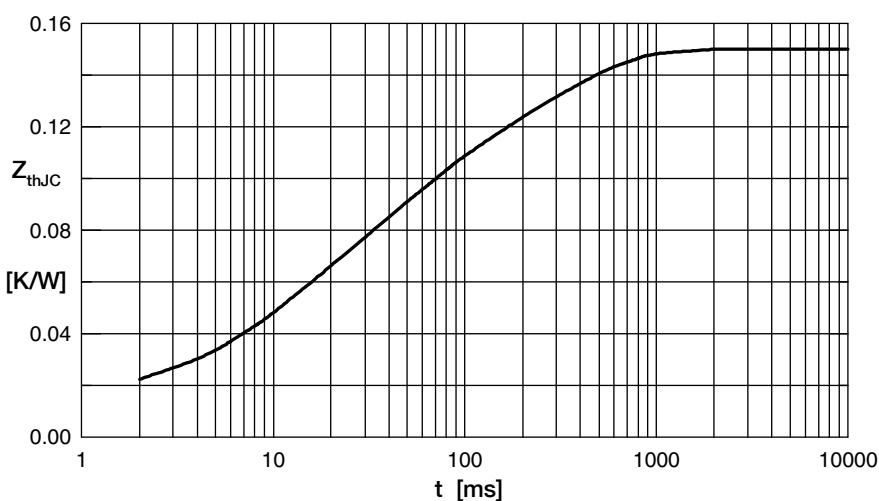
Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R Fig. 4a Power dissipation versus direct output current
Fig. 4b and ambient temperatureFig. 5 Average forward current $I_{F(AV)}$ vs. case temp. T_C 

Fig. 6 Transient thermal impedance junction to case

R_{thi} [K/W]	t_i [s]
0.017	0.01
0.013	0.00001
0.02	0.01
0.05	0.045
0.05	0.3